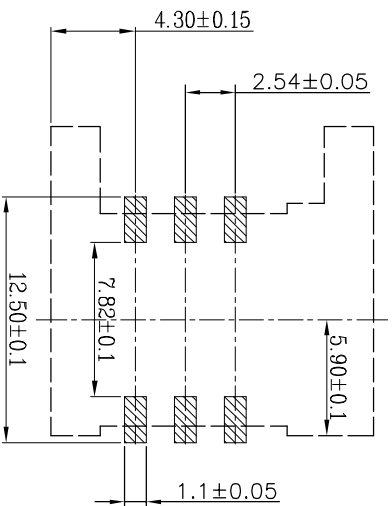
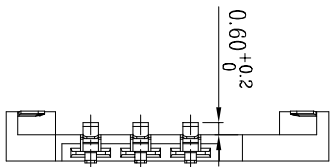
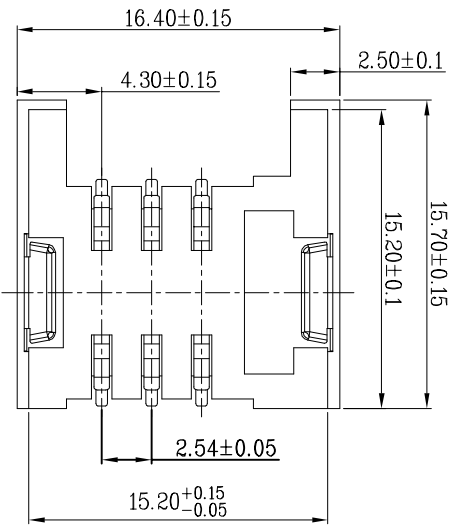


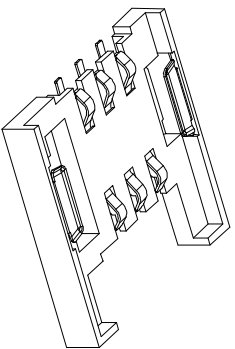
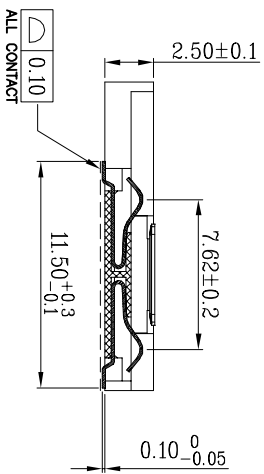
REV. ECN NO OR DESCRIPTION	REVISED DATE
A PRELIMINARY	JASMINE 05/12/15



RECOMMENDED PCB FOOTPRINTING

SPECIFICATION:

- 1. MATERIALS:**
 1-1. HOUSING: ICP U194V-0, BLACK
 1-2. CONTACT SPRING: PHOSPHOR BRONZE.
 1-3. PLATING: CONTACT Au 15u", SOLDER Au 3u",
 ON ALL AREA OVER 80u" Ni;
2. ELECTRICAL CHARACTERISTICS:
 2-1. CURRENT RATING 0.5 Amp. MAX. PER CONTACT.
 2-2. LOW LEVEL CONTACT RESISTANCE 100 mohms MAX. AFTER CONDITIONS.
 INITIAL DIFFERENCE OF 20 mohms MAX. AFTER CONDITIONS.
 2-3. DIELECTRIC WITHSTANDING VOLTAGE 500V AC MIN. FOR 1
 MINUTE WITH 1 mAmp MAX. CURRENT LEAKAGE.
 2-4. INSULATION RESISTANCE 1000 Mohms MIN. INITIAL AT 500V DC,
 100 Mohms MIN. AFTER CONDITION AT 500V DC.
3. MECHANICAL CHARACTERISTICS:
 3-1. CONTACT NORMAL FORCE: 0.31-0.50 N.
 3-2. DURABILITY 10000 MATING/UNMATING CYCLES.
4. ENVIRONMENTAL CHARACTERISTICS:
 4-1. OPERATING TEMPERATURE -55°C TO +85°C.
 4-2. VIBRATION NO DISCONTINUITIES GREATER THAN 100 ns.
 5. SOLDER HEAT RESISTANCE: WAVE SOLDERING 260°C 10 SECS.
 6. TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE"
 7. GREEN PRODUCT IDENTIFICATION LABEL IN PACKING: [E2] [PASS]
 8. FOR WAVE SOLDERING LEAD-FREE PROCESS.



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS:	ANGLES:			
X : ±0.5	X : ±2°			
X.X : ±0.3	X.X : ±1°			
X.XX : ±0.2				
TITLE	SIM CARD CONNECTOR<2.5H>			
DWN	Jasmine/12/15/16 P&T NO.2SM-P025-001			
CHKD	SCALE: UNIT: mm			
APVD	SIZE: A3 SHEET: 1 OF 1 REV: A			

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Singatron Enterprise Co., Ltd.
 信亨電子(中山)有限公司